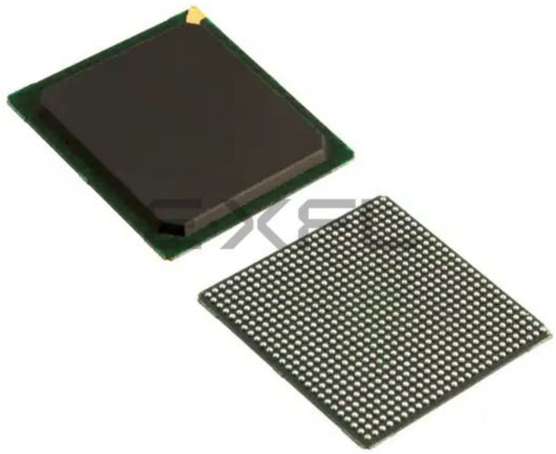

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18144
Number of Logic Elements/Cells	-
Total RAM Bits	165888
Number of I/O	418
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax1000-2fg676

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

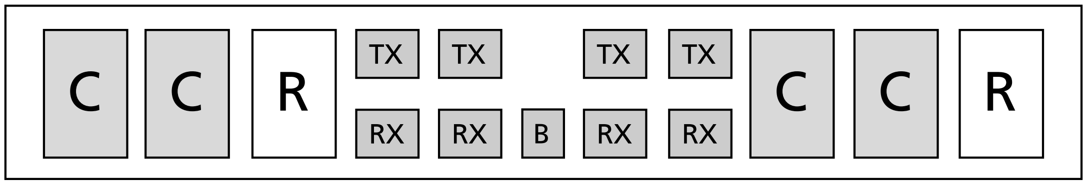


Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

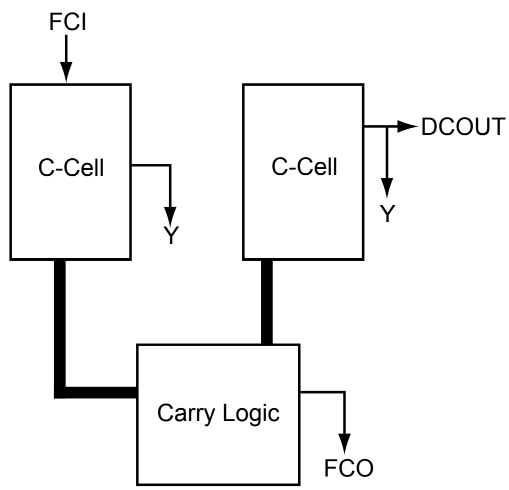


Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

***Table 1-1* • Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

The SRAM blocks are arranged in a column on the west side of the tile (Figure 1-6 on page 1-4).

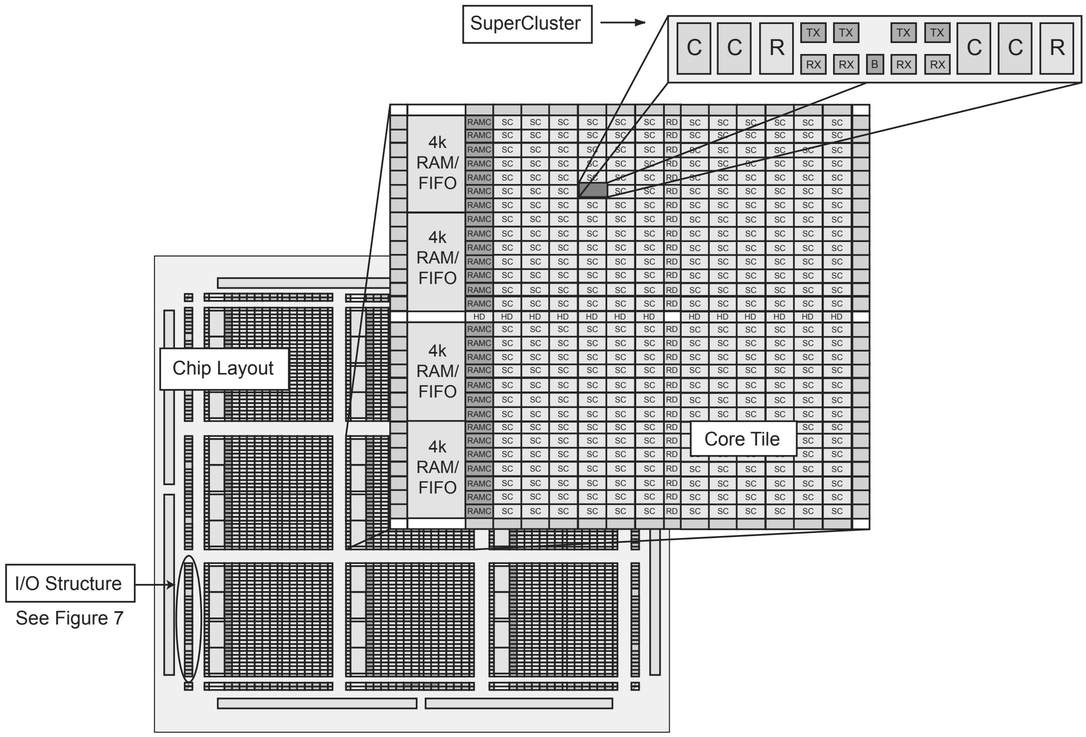


Figure 1-6 • **AX Device Architecture (AX1000 shown)**

Embedded Memory

As mentioned earlier, each core tile has either three (in a smaller tile) or four (in the regular tile) embedded SRAM blocks along the west side, and each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are: 128x36, 256x18, 512x9, 1kx4, 2kx2 or 4kx1 bits. The individual blocks have separate read and write ports that can be configured with different bit widths on each port. For example, data can be written in by eight and read out by one.

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using core logic modules. The FIFO width and depth are programmable. The FIFO also features programmable ALMOST-EMPTY (AEMPTY) and ALMOST-FULL (AFULL) flags in addition to the normal EMPTY and FULL flags. In addition to the flag logic, the embedded FIFO control unit also contains the counters necessary for the generation of the read and write address pointers as well as control circuitry to prevent metastability and erroneous operation. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

I/O Logic

The Axcelerator family of FPGAs features a flexible I/O structure, supporting a range of mixed voltages with its bank-selectable I/Os: 1.5V, 1.8V, 2.5V, and 3.3V. In all, Axcelerator FPGAs support at least 14 different I/O standards (single-ended, differential, voltage-referenced). The I/Os are organized into banks, with eight banks per device (two per side). The configuration of these banks determines the I/O standards supported (see "User I/Os" on page 2-11 for more information). All I/O standards are available in each bank.

Each I/O module has an input register (InReg), an output register (OutReg), and an enable register (EnReg) (Figure 1-7 on page 1-5). An I/O Cluster includes two I/O modules, four RX modules, two TX modules, and a buffer (B) module.

Design Environment

The Axcelerator family of FPGAs is fully supported by both Microsemi's Libero® Integrated Design Environment and Designer FPGA Development software. Libero IDE is an integrated design manager that seamlessly integrates design tools while guiding the user through the design flow, managing all design and log files, and passing necessary design data among tools. Additionally, Libero IDE allows users to integrate both schematic and HDL synthesis into a single flow and verify the entire design in a single environment (see the *Libero IDE Flow* diagram located on the Microsemi SoC Products Group website). Libero IDE includes Synplify® Actel Edition (AE) from Synplicity®, ViewDraw® AE from Mentor Graphics®, Model*Sim*® HDL Simulator from Mentor Graphics, WaveFormer Lite™ AE from SynaptiCAD®, and Designer software from Microsemi.

Designer software is a place-and-route tool and provides a comprehensive suite of backend support tools for FPGA development. The Designer software includes the following:

- Timer – a world-class integrated static timing analyzer and constraints editor which support timing-driven place-and-route
- NetlistViewer – a design netlist schematic viewer
- ChipPlanner – a graphical floorplanner viewer and editor
- SmartPower – allows the designer to quickly estimate the power consumption of a design
- PinEditor – a graphical application for editing pin assignments and I/O attributes
- I/O Attribute Editor – displays all assigned and unassigned I/O macros and their attributes in a spreadsheet format

With the Designer software, a user can lock the design pins before layout while minimally impacting the results of place-and-route. Additionally, Microsemi's back-annotation flow is compatible with all the major simulators and the simulation results can be cross-probed with Silicon Explorer II, Microsemi's integrated verification and logic analysis tool. Another tool included in the Designer software is the SmartGen core generator, which easily creates popular and commonly used logic functions for implementation into your schematic or HDL design.

Designer software is compatible with the most popular FPGA design entry and verification tools from EDA vendors, such as Mentor Graphics, Synplicity, Synopsys, and Cadence Design Systems. The Designer software is available for both the Windows and UNIX operating systems.

Programming

Programming support is provided through Silicon Sculptor II, a single-site programmer driven via a PC-based GUI. In addition, BP Microsystems offers multi-site programmers that provide qualified support for Microsemi devices. Factory programming is available for high-volume production needs.

In-System Diagnostic and Debug Capabilities

The Axcelerator family of FPGAs includes internal probe circuitry, allowing the designer to dynamically observe and analyze any signal inside the FPGA without disturbing normal device operation (Figure 1-9).

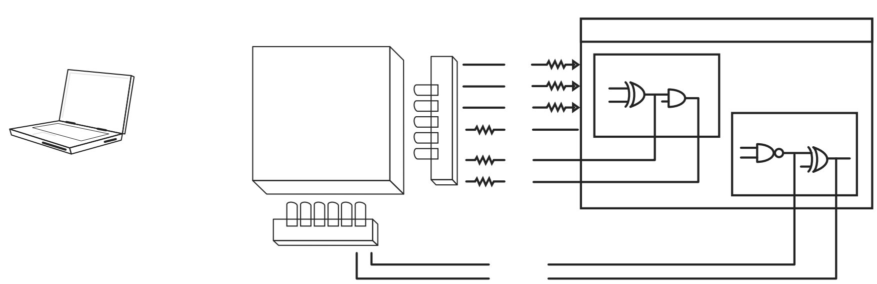


Figure 1-9 • **Probe Setup**

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

VCCA	Junction Temperature						
	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

Timing Characteristics

Table 2-28 • 1.8V LVCMOS I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.7 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS18 Output Module Timing								
t_{DP}	Input Buffer		3.26		3.71		4.37	ns
t_{PY}	Output Buffer		4.55		5.18		6.09	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.82		2.83		2.84	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		3.43		3.45		3.46	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.01		6.85		8.05	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.73		7.67		9.01	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Module Specifications

C-Cell

Introduction

The C-cell is one of the two logic module types in the AX architecture. It is the combinatorial logic resource in the Axcelerator device. The AX architecture implements a new combinatorial cell that is an extension of the C-cell implemented in the SX-A family. The main enhancement of the new C-cell is the addition of carry-chain logic.

The C-cell can be used in a carry-chain mode to construct arithmetic functions. If carry-chain logic is not required, it can be disabled.

The C-cell features the following (Figure 2-27):

- Eight-input MUX (data: D0-D3, select: A0, A1, B0, B1). User signals can be routed to any one of these inputs. Any of the C-cell inputs (D0-D3, A0, A1, B0, B1) can be tied to one of the four routed clocks (CLKE/F/G/H).
- Inverter (DB input) can be used to drive a complement signal of any of the inputs to the C-cell.
- A carry input and a carry output. The carry input signal of the C-cell is the carry output from the C-cell directly to the north.
- Carry connect for carry-chain logic with a signal propagation time of less than 0.1 ns.
- A hardwired connection (direct connect) to the adjacent R-cell (Register Cell) for all C-cells on the east side of a SuperCluster with a signal propagation time of less than 0.1 ns.

This layout of the C-cell (and the C-cell Cluster) enables the implementation of over 4,000 functions of up to five bits. For example, two C-cells can be used together to implement a four-input XOR function in a single cell delay.

The carry-chain configuration is handled automatically for the user with Microsemi's extensive macro library (please see the *Antifuse Macro Library Guide* for a complete listing of available Axcelerator macros).

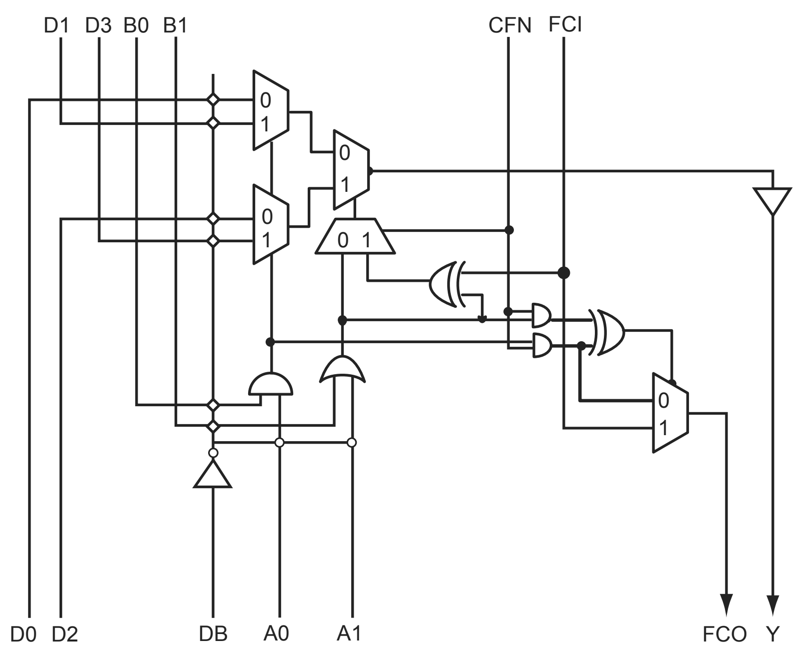


Figure 2-27 • **C-Cell**

PLLRCLK and PLLHCLK

PLLRCLK (PLLHCLK) is used to drive global resource CLK (HCLK) from a PLL (Figure 2-44).

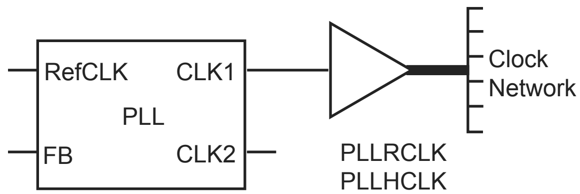


Figure 2-44 **• PLLRCLK and PLLHCLK**

Using Global Resources with PLLs

Each global resource has an associated PLL at its root. For example, PLLA can drive HCLKA, PLLE can drive CLKE, etc. (Figure 2-45).

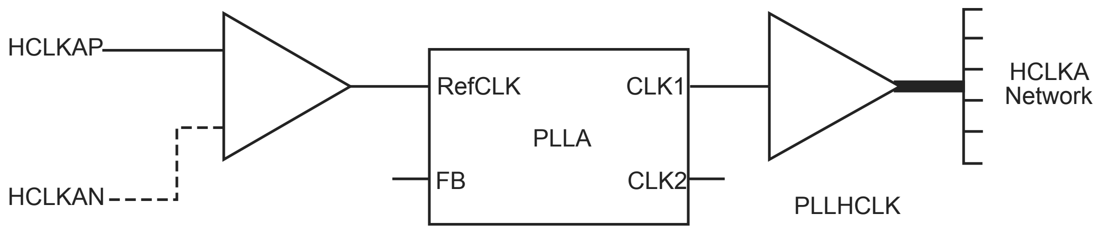


Figure 2-45 **• Example of HCLKA Driven from a PLL with External Clock Source**

In addition, each clock pin of the package can be used to drive either its associated global resource or PLL. For example, package pins CLKEP and CLKEN can drive either the RefCLK input of PLLE or CLKE.

There are two macros required when interfacing the embedded PLLs with the global resources: PLLINT and PLLOUT.

PLLINT

This macro is used to drive the RefCLK input of the PLL internally from user signals.

PLLOUT

This macro is used to connect either the CLK1 or CLK2 output of a PLL to the regular routing network (Figure 2-46).

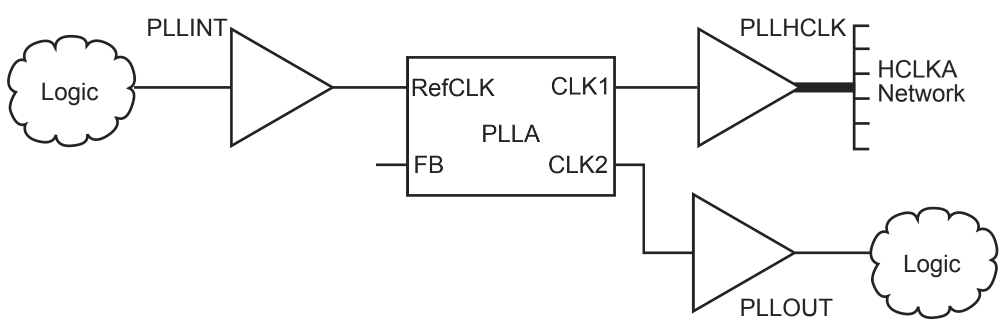


Figure 2-46 **• Example of PLLINT and PLLOUT Usage**

***Table 2-80* • PLL Interface Signals**

Signal Name	Type	User Accessible	Allowable Values	Function
RefCLK	Input	Yes		Reference Clock for the PLL
FB	Input	Yes		Feedback port for the PLL
PowerDown	Input	Yes		PLL power down control
			0	PLL powered down
			1	PLL active
DIVI[5:0]	Input	Yes	1 to 64, in unsigned binary notation offset by -1	Sets value for feedback divider (multiplier)
DIVJ[5:0]	Input	Yes		Sets value for CLK1 divider
LowFreq	Input	Yes		Input frequency range selector
			0	50–200 MHz
			1	14–50 MHz
Osc[2:0]	Input	Yes		Output frequency range selector
			XX0	400–1000 MHZ
			001	200–400 MHZ
			011	100–200 MHZ
			101	50–100 MHZ
			111	20–50 MHZ
DelayLine[4:0]	Input	Yes	–15 to +15 (increments), in signed-and-magnitude binary representation	Clock Delay (positive/negative) in increments of 250 ps, with maximum value of ± 3.75 ns
FBMuxSel	Input	No		Selects the source for the feedback input
REFSEL	Input	No		Selects the source for the reference clock
OUTSEL	Input	No		Selects the source for the routed net output
PLLSEL	Input	No		ROOTSEL & PLLSEL are used to select the source of the global clock network
ROOTSEL	Input	No		
Lock	Output	Yes		High value indicates PLL has locked
CLK1	Output	Yes		PLL clock output
CLK2	Output	Yes		PLL clock output

Note: If the input RefClk is taken outside its operating range, the outputs Lock, CLK1 and CLK2 are indeterminate.

Programming

Device programming is supported through the Silicon Sculptor II, a single-site, robust and compact device programmer for the PC. Up to four Silicon Sculptor IIs can be daisy-chained and controlled from a single PC host. With standalone software for the PC, Silicon Sculptor II is designed to allow concurrent programming of multiple units from the same PC when daisy-chained.

Silicon Sculptor II programs devices independently to achieve the fastest programming times possible. Each fuse is verified by Silicon Sculptor II to ensure correct programming. Furthermore, at the end of programming, there are integrity tests that are run to ensure that programming was completed properly. Not only does it test programmed and nonprogrammed fuses, Silicon Sculptor II also provides a self-test to test its own hardware extensively.

Programming an Axcelerator device using Silicon Sculptor II is similar to programming any other antifuse device. The procedure is as follows:

1. Load the *.AFM file.
2. Select the device to be programmed.
3. Begin programming.

When the design is ready to go to production, Microsemi offers device volume-programming services either through distribution partners or via our In-House Programming Center.

In addition, BP Microsystems offers multi-site programmers that provide qualified support for Axcelerator devices.

For more details on programming the Axcelerator devices, please refer to the *Silicon Sculptor II User's Guide*.

BG729	
AX1000 Function	Pin Number
VCCIB0	B4
VCCIB0	C4
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K12
VCCIB0	K13
VCCIB1	A24
VCCIB1	B24
VCCIB1	C24
VCCIB1	J16
VCCIB1	J17
VCCIB1	J18
VCCIB1	K15
VCCIB1	K16
VCCIB2	D25
VCCIB2	D26
VCCIB2	D27
VCCIB2	K19
VCCIB2	L19
VCCIB2	M18
VCCIB2	M19
VCCIB2	N18
VCCIB3	AD25
VCCIB3	AD26
VCCIB3	AD27
VCCIB3	R18
VCCIB3	T18
VCCIB3	T19
VCCIB3	U19
VCCIB3	V19
VCCIB4	AE24
VCCIB4	AF24
VCCIB4	AG24
VCCIB4	V15
VCCIB4	V16
VCCIB4	W16

BG729	
AX1000 Function	Pin Number
VCCIB4	W17
VCCIB4	W18
VCCIB5	AE4
VCCIB5	AF4
VCCIB5	AG4
VCCIB5	V12
VCCIB5	V13
VCCIB5	W10
VCCIB5	W11
VCCIB5	W12
VCCIB6	AD1
VCCIB6	AD2
VCCIB6	AD3
VCCIB6	R10
VCCIB6	T10
VCCIB6	T9
VCCIB6	U9
VCCIB6	V9
VCCIB7	D1
VCCIB7	D2
VCCIB7	D3
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCOMPLA	B13
VCOMPLB	A14
VCOMPLC	A15
VCOMPLD	J15
VCOMPLE	AG15
VCOMPLF	W15
VCOMPLG	AC14
VCOMPLH	W13
VPUMP	D24

FG484	
AX500 Function	Pin Number
Bank 0	
IO00NB0F0	E3
IO00PB0F0	D3
IO01NB0F0	E7
IO01PB0F0	E6
IO02NB0F0	C5
IO02PB0F0	C4
IO03NB0F0	D7
IO03PB0F0	D6
IO04NB0F0	B5
IO04PB0F0	B4
IO05NB0F0	C7
IO05PB0F0	C6
IO06NB0F0	A5
IO06PB0F0	A4
IO07NB0F0	A7
IO07PB0F0	A6
IO08NB0F0	B7
IO08PB0F0	B6
IO10NB0F0	B9
IO10PB0F0	B8
IO11NB0F0	E9
IO11PB0F0	E8
IO12NB0F1	D9
IO12PB0F1	D8
IO13NB0F1	C9
IO13PB0F1	C8
IO14NB0F1	A9
IO14PB0F1	A8
IO15NB0F1	B10
IO15PB0F1	A10
IO16NB0F1	B12
IO16PB0F1	B11
IO18NB0F1	C13
IO18PB0F1	C12
IO19NB0F1/HCLKAN	E11
IO19PB0F1/HCLKAP	E10
IO20NB0F1/HCLKBN	D12
IO20PB0F1/HCLKBP	D11
Bank 1	
IO21NB1F2/HCLKCN	F13
IO21PB1F2/HCLKCP	F12
IO22NB1F2/HCLKDN	E14
IO22PB1F2/HCLKDP	E13
IO24NB1F2	A14
IO24PB1F2	A13
IO25NB1F2	B14
IO25PB1F2	B13
IO26NB1F2	C15
IO27NB1F2	A16
IO27PB1F2	A15
IO28NB1F2	B16
IO28PB1F2	B15
IO29NB1F2	D16
IO29PB1F2	D15
IO30NB1F2	A18
IO30PB1F2	A17
IO31NB1F2	F15
IO31PB1F2	F14
IO32NB1F3	C17
IO32PB1F3	C16
IO33NB1F3	E16
IO33PB1F3	E15
IO34NB1F3	B18
IO34PB1F3	B17
IO35NB1F3	B19
IO35PB1F3	A19
IO36NB1F3	C19
IO36PB1F3	C18
IO37NB1F3	F18
IO37PB1F3	F17
IO38NB1F3	D18
IO38PB1F3	E17
IO39NB1F3	E21
IO39PB1F3	D21
IO40NB1F3	E20
IO40PB1F3	D20
IO41NB1F3	G16
IO41PB1F3	G15
Bank 2	
IO42NB2F4	F19
IO42PB2F4	E19
IO43NB2F4	J16
IO43PB2F4	H16
IO44NB2F4	E22
IO44PB2F4	D22
IO45NB2F4	H19
IO45PB2F4	G19
IO46NB2F4	G22
IO46PB2F4	F22
IO47NB2F4	J17
IO47PB2F4	H17
IO48NB2F4	G20
IO48PB2F4	F20
IO49NB2F4	J18
IO49PB2F4	H18
IO50NB2F4	G21
IO50PB2F4	F21
IO51NB2F4	K19
IO51PB2F4	J19
IO52NB2F5	J21
IO52PB2F5	H21
IO53NB2F5	J20
IO53PB2F5	H20
IO54NB2F5	J22

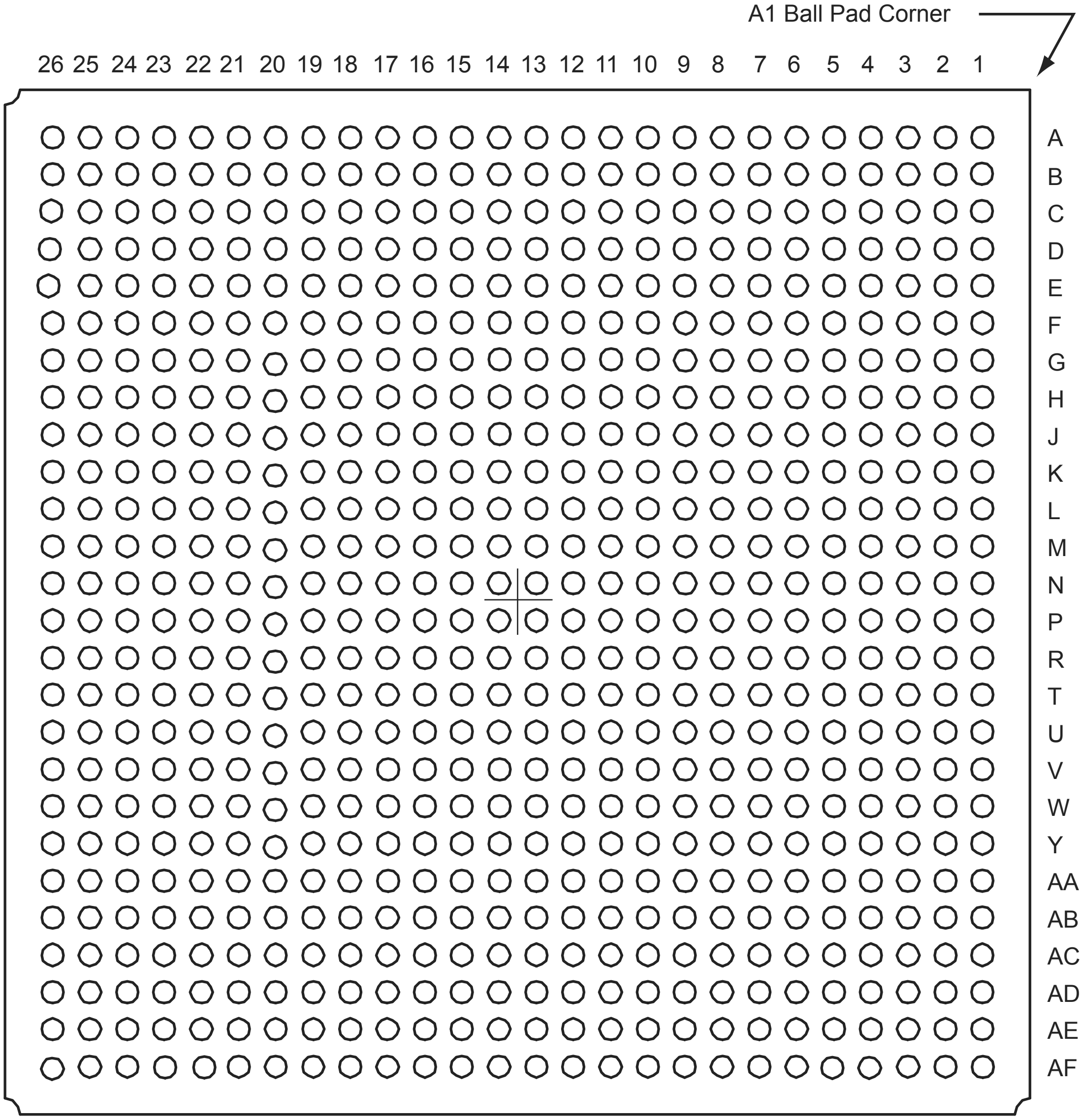
FG484	
AX500 Function	**Pin Number**
IO54PB2F5	H22
IO55NB2F5	L17
IO55PB2F5	K17
IO56NB2F5	K21
IO56PB2F5	K22
IO58NB2F5	L20
IO58PB2F5	K20
IO59NB2F5	L18
IO59PB2F5	K18
IO60NB2F5	M21
IO60PB2F5	L21
IO61NB2F5	L16
IO61PB2F5	K16
IO62NB2F5	M19
IO62PB2F5	L19
Bank 3	
IO63NB3F6	N16
IO63PB3F6	M16
IO64NB3F6	P22
IO64PB3F6	N22
IO65NB3F6	N20
IO65PB3F6	M20
IO66NB3F6	P21
IO66PB3F6	N21
IO67NB3F6	N18
IO67PB3F6	N19
IO68NB3F6	T22
IO68PB3F6	R22
IO69NB3F6	N17
IO69PB3F6	M17
IO70NB3F6	T21
IO70PB3F6	R21
IO71NB3F6	P18
IO71PB3F6	P19
IO72NB3F6	R20

FG484	
AX500 Function	**Pin Number**
IO72PB3F6	P20
IO73PB3F6	R19
IO74NB3F7	V21
IO74PB3F7	U21
IO75NB3F7	V22
IO75PB3F7	U22
IO76NB3F7	U20
IO76PB3F7	T20
IO77NB3F7	R17
IO77PB3F7	P17
IO78NB3F7	W21
IO78PB3F7	W22
IO79NB3F7	T18
IO79PB3F7	R18
IO80NB3F7	W20
IO80PB3F7	V20
IO81NB3F7	U19
IO81PB3F7	T19
IO82NB3F7	U18
IO82PB3F7	V19
IO83NB3F7	R16
IO83PB3F7	P16
Bank 4	
IO84NB4F8	AB18
IO84PB4F8	AB19
IO85NB4F8	T15
IO85PB4F8	T16
IO86NB4F8	AA18
IO86PB4F8	AA19
IO87NB4F8	W17
IO87PB4F8	V17
IO88NB4F8	Y19
IO88PB4F8	W18
IO89NB4F8	U14
IO89PB4F8	U15

FG484	
AX500 Function	**Pin Number**
IO90NB4F8	Y17
IO90PB4F8	Y18
IO91NB4F8	V15
IO91PB4F8	V16
IO92PB4F8	AB17
IO93NB4F8	Y15
IO93PB4F8	Y16
IO94NB4F9	AA16
IO94PB4F9	AA17
IO95NB4F9	AB14
IO95PB4F9	AB15
IO96NB4F9	W15
IO96PB4F9	W16
IO97NB4F9	AA13
IO97PB4F9	AB13
IO98NB4F9	AA14
IO98PB4F9	AA15
IO100NB4F9	Y14
IO100PB4F9	W14
IO101NB4F9	Y12
IO101PB4F9	Y13
IO102NB4F9	AA11
IO102PB4F9	AA12
IO103NB4F9/CLKEN	V12
IO103PB4F9/CLKEP	V13
IO104NB4F9/CLKFN	W11
IO104PB4F9/CLKFP	W12
Bank 5	
IO105NB5F10/CLKGN	U10
IO105PB5F10/CLKGP	U11
IO106NB5F10/CLKHN	V9
IO106PB5F10/CLKHP	V10
IO107NB5F10	Y10
IO107PB5F10	Y11
IO108NB5F10	AA9

FG484		FG484		FG484	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO246NB7F22	F3	GND	D4	GND	V5
IO246PB7F22	G3	GND	E18	GND	W19
IO250NB7F23	F4	GND	E5	GND	W4
IO250PB7F23	G4	GND	G18	GND	Y20
IO253NB7F23	G5	GND	H15	GND	Y3
IO253PB7F23	G6	GND	H8	GND/LP	G7
IO254NB7F23	D1	GND	J14	PRA	G11
IO254PB7F23	E1	GND	J9	PRB	F11
IO257NB7F23	F5	GND	K10	PRC	T12
IO257PB7F23	E4	GND	K11	PRD	U12
Dedicated I/O		GND	K12	TCK	G8
VCCDA	H7	GND	K13	TDI	F9
GND	A1	GND	L1	TDO	F7
GND	A11	GND	L10	TMS	F6
GND	A12	GND	L11	TRST	F8
GND	A2	GND	L12	VCCA	G17
GND	A21	GND	L13	VCCA	J10
GND	A22	GND	L22	VCCA	J11
GND	AA1	GND	M1	VCCA	J12
GND	AA2	GND	M10	VCCA	J13
GND	AA21	GND	M11	VCCA	J7
GND	AA22	GND	M12	VCCA	K14
GND	AB1	GND	M13	VCCA	K9
GND	AB11	GND	M22	VCCA	L14
GND	AB12	GND	N10	VCCA	L9
GND	AB2	GND	N11	VCCA	M14
GND	AB21	GND	N12	VCCA	M9
GND	AB22	GND	N13	VCCA	N14
GND	B1	GND	P14	VCCA	N9
GND	B2	GND	P9	VCCA	P10
GND	B21	GND	R15	VCCA	P11
GND	B22	GND	R8	VCCA	P12
GND	C20	GND	U16	VCCA	P13
GND	C3	GND	U6	VCCA	T6
GND	D19	GND	V18	VCCA	U17

FG676



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896	
AX1000 Function	Pin Number
IO206PB6F19	AB4
IO207NB6F19	W6
IO207PB6F19	W7
IO208NB6F19	AB3
IO208PB6F19	AC3
IO209NB6F19	V8
IO209PB6F19	V9
IO210NB6F19	AA2
IO210PB6F19	AA1
IO211NB6F19	V5
IO211PB6F19	W5
IO212NB6F19	Y3
IO212PB6F19	Y4
IO213NB6F19	V7
IO213PB6F19	V6
IO214NB6F20	W3
IO214PB6F20	W4
IO215NB6F20	U8
IO215PB6F20	U9
IO216NB6F20	W1
IO216PB6F20	W2
IO217NB6F20	U7
IO217PB6F20	U6
IO218NB6F20	U4
IO218PB6F20	V4
IO219NB6F20	T5
IO219PB6F20	U5
IO220NB6F20	U3
IO220PB6F20	V3
IO221NB6F20	T8
IO221PB6F20	T9
IO222NB6F20	U2
IO222PB6F20	V2
IO223NB6F20	T7
IO223PB6F20	T6

FG896	
AX1000 Function	Pin Number
IO224NB6F20	R2
IO224PB6F20	T2
Bank 7	
IO225NB7F21	R7
IO225PB7F21	R6
IO226NB7F21	R4
IO226PB7F21	R5
IO227NB7F21	R8
IO227PB7F21	R9
IO228NB7F21	P1
IO228PB7F21	R1
IO229NB7F21	P9
IO229PB7F21	P8
IO230NB7F21	N2
IO230PB7F21	P2
IO231NB7F21	P7
IO231PB7F21	P6
IO232NB7F21	N3
IO232PB7F21	P3
IO233NB7F21	P4
IO233PB7F21	P5
IO234NB7F21	L1
IO234PB7F21	M1
IO235NB7F21	M4
IO235PB7F21	N4
IO236NB7F22	N7
IO236PB7F22	N6
IO237NB7F22	N8
IO237PB7F22	N9
IO238NB7F22	M5
IO238PB7F22	N5
IO239NB7F22	L2
IO239PB7F22	M2
IO240NB7F22	L3
IO240PB7F22	M3

FG896	
AX1000 Function	Pin Number
IO241NB7F22	M8
IO241PB7F22	M7
IO242NB7F22	K4
IO242PB7F22	L4
IO243NB7F22	L6
IO243PB7F22	M6
IO244NB7F22	K5
IO244PB7F22	L5
IO245NB7F22	J4
IO245PB7F22	J3
IO246NB7F22	G2
IO246PB7F22	H2
IO247NB7F23	L8
IO247PB7F23	L7
IO248NB7F23	G3
IO248PB7F23	H3
IO249NB7F23	G4
IO249PB7F23	H4
IO250NB7F23	J6
IO250PB7F23	K6
IO251NB7F23	H5
IO251PB7F23	J5
IO252NB7F23	F2
IO252PB7F23	F1
IO253NB7F23	K8
IO253PB7F23	K7
IO254NB7F23	F4
IO254PB7F23	F3
IO255NB7F23	G6
IO255PB7F23	H6
IO256NB7F23	F5
IO256PB7F23	G5
IO257NB7F23	H7
IO257PB7F23	J7
Dedicated I/O	

FG896	
AX2000 Function	Pin Number
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10

FG896	
AX2000 Function	Pin Number
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

FG1152	
AX2000 Function	Pin Number
IO103PB2F9	M28
IO104NB2F9	M34
IO104PB2F9	L34
IO105NB2F9	P27
IO105PB2F9	N27
IO106NB2F9	M32
IO106PB2F9	M31
IO107NB2F10	P25
IO107PB2F10	P26
IO108NB2F10	N33
IO108PB2F10	M33
IO109NB2F10	P29
IO109PB2F10	N29
IO110NB2F10	P30
IO110PB2F10	N30
IO111NB2F10	R24
IO111PB2F10	R25
IO112NB2F10	P31
IO112PB2F10	N31
IO113NB2F10	R28
IO113PB2F10	P28
IO114NB2F10	P32
IO114PB2F10	N32
IO115NB2F10	R30
IO115PB2F10	R29
IO116NB2F10	P34
IO116PB2F10	P33
IO117NB2F10	R27
IO117PB2F10	R26
IO118NB2F11	R34
IO118PB2F11	R33
IO119NB2F11	T24
IO119PB2F11	T25
IO120NB2F11	T33
IO120PB2F11	T34

FG1152	
AX2000 Function	Pin Number
IO121NB2F11	T27
IO121PB2F11	T26
IO122NB2F11	T30
IO122PB2F11	T29
IO123NB2F11	U28
IO123PB2F11	T28
IO124NB2F11	T31
IO124PB2F11	T32
IO125NB2F11	U24
IO125PB2F11	U25
IO126NB2F11	U33
IO126PB2F11	U34
IO127NB2F11	U26
IO127PB2F11	U27
IO128NB2F11	U31
IO128PB2F11	U32
Bank 3	
IO129NB3F12	V29
IO129PB3F12	U29
IO130NB3F12	V31
IO130PB3F12	V32
IO131NB3F12	V24
IO131PB3F12	V25
IO132NB3F12	W28
IO132PB3F12	V28
IO133NB3F12	W26
IO133PB3F12	V26
IO134NB3F12	W33
IO134PB3F12	V33
IO135NB3F12	W25
IO135PB3F12	W24
IO136NB3F12	W31
IO136PB3F12	W32
IO137NB3F12	Y30
IO137PB3F12	W30

FG1152	
AX2000 Function	Pin Number
IO138NB3F12	Y29
IO138PB3F12	W29
IO139NB3F13	Y27
IO139PB3F13	W27
IO140NB3F13	AA33
IO140PB3F13	Y33
IO141NB3F13	Y25
IO141PB3F13	Y24
IO142NB3F13	AA31
IO142PB3F13	Y31
IO143NB3F13	AA28
IO143PB3F13	Y28
IO144NB3F13	AA34
IO144PB3F13	Y34
IO145NB3F13	AA26
IO145PB3F13	Y26
IO146NB3F13	AA29
IO146PB3F13	AA30
IO147NB3F13	AB30
IO147PB3F13	AB29
IO148NB3F13	AB32
IO148PB3F13	AA32
IO149NB3F13	AB27
IO149PB3F13	AA27
IO150NB3F14	AC31
IO150PB3F14	AB31
IO151NB3F14	AD33
IO151PB3F14	AC33
IO152NB3F14	AC28
IO152PB3F14	AB28
IO153NB3F14	AB25
IO153PB3F14	AA25
IO154NB3F14	AD32
IO154PB3F14	AC32
IO155NB3F14	AD29

CQ352	
AX250 Function	**Pin Number**
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX250 Function	**Pin Number**
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CG624	
AX2000 Function	Pin Number
Bank 0	
IO00NB0F0	D7*
IO00PB0F0	E7*
IO01NB0F0	G7
IO01PB0F0	G6
IO02NB0F0	B5
IO02PB0F0	B4
IO04PB0F0	C7
IO05NB0F0	F8
IO05PB0F0	F7
IO06NB0F0	H8
IO06PB0F0	H7
IO11NB0F0	J8
IO11PB0F0	J7
IO12PB0F1	B6
IO13NB0F1	E9*
IO13PB0F1	D8*
IO15NB0F1	C9
IO15PB0F1	C8
IO16NB0F1	A5
IO16PB0F1	A4
IO17NB0F1	D10
IO17PB0F1	D9
IO18NB0F1	A7
IO18PB0F1	A6
IO19NB0F1	G9
IO19PB0F1	G8
IO20PB0F1	B7
IO23NB0F2	F10
IO23PB0F2	F9
IO26NB0F2	C11*
IO26PB0F2	B8*

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO27NB0F2	H10
IO27PB0F2	H9
IO28NB0F2	A9
IO28PB0F2	B9
IO30NB0F2	B11
IO30PB0F2	B10
IO31NB0F2	E11
IO31PB0F2	F11
IO33NB0F2	D12
IO33PB0F2	D11
IO34NB0F3	A11
IO34PB0F3	A10
IO37NB0F3	J13
IO37PB0F3	K13
IO38NB0F3	H11
IO38PB0F3	G11
IO40PB0F3	B12
IO41NB0F3/HCLKAN	G13
IO41PB0F3/HCLKAP	G12
IO42NB0F3/HCLKBN	C13
IO42PB0F3/HCLKBP	C12
Bank 1	
IO43NB1F4/HCLKCN	G15
IO43PB1F4/HCLKCP	G14
IO44NB1F4/HCLKDN	B14
IO44PB1F4/HCLKDP	B13
IO45NB1F4	H13
IO47NB1F4	D14
IO47PB1F4	C14
IO48NB1F4	A16
IO48PB1F4	A15
IO49PB1F4	H15

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO51NB1F4	E15
IO51PB1F4	F15
IO52NB1F4	A17
IO55NB1F5	G16
IO55PB1F5	H16
IO56NB1F5	A20
IO56PB1F5	A19
IO57NB1F5	D16
IO57PB1F5	D15
IO58NB1F5	A22
IO58PB1F5	A21
IO59NB1F5	F16
IO61NB1F5	G17
IO61PB1F5	H17
IO62NB1F5	B17
IO62PB1F5	B16
IO63NB1F5	H18
IO65NB1F6	C17
IO66PB1F6	B18
IO67NB1F6	J18
IO67PB1F6	J19
IO68NB1F6	B20
IO68PB1F6	B19
IO69NB1F6	E17
IO69PB1F6	F17
IO70NB1F6	B22
IO70PB1F6	B21
IO71PB1F6	G18
IO73NB1F6	G19
IO74NB1F6	C19
IO74PB1F6	C18
IO75NB1F6	D18

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

Revision	Changes	Page
Revision 8 (continued)	The following changes were made in the "FG676"(AX500) section: AE2, AE25 — Change from NC to GND. AF2, AF25 — Changed from GND to NC AB4, AF24, C1, C26 — Changed from V_{CCDA} to V_{CCA} AD15 — Change from V_{CCDA} to V_{COMPLE} AD17 — Changed from V_{COMPLE} to V_{CCDA}	3-37
	In the "FG896" (AX2000) section, the AK28 changed from VCCIB5 to VCCIB4.	3-52
	The "CQ352" and "CG624" sections are new.	3-98, 3-115
Revision 7 (Advance v1.6)	All I/O FIFO capability was removed.	n/a
	Table 1 was updated.	i
	Figure 1-9 was updated.	1-7
	Figure 2-5 was updated.	2-16
	The "Using an I/O Register" section was updated.	2-16
	The AX250 and AX1000 descriptions were added to the "FG484"section.	3-21
Revision 6 (Advance v1.5)	Table 2-3 was updated.	2-2
	Figure 2-1 was updated.	2-8
	Figure 2-48 was updated.	2-75
	Figure 2-52 was updated.	2-82
Revision 5 (Advance v1.4)	In the "PQ208" table, pin 196 was missing, but it has been added in this version with a function of GND.	3-84
	The following pins in the "FG484" table for AX500 were changed: Pin G7 is GND/LP Pins AB8, C10, C11, C14, AB16 are NC.	3-21
	The "FG676" table was updated.	3-37
Revision 4 (Advance v1.3)	The "Device Resources" section was updated for the CS180.	ii
	The "Programmable Interconnect Element" and Figure 1-2 are new.	1-1 and 1-2
	The "CS180" table is new.	3-1
	The "PQ208" tables for the AX500 were updated. The following pins were not defined in the previous version: GND 21 IO106PB5F10/CLKHP 71 GND 136	3-84
Revision 3 (Advance v1.2)	Table 1, "Ordering Information", "Device Resources", and the Product Plan table were updated.	i, ii
	The following figures and tables were updated: Figure 1-3 Figure 1-8 (new) Table 2-3 Figure 2-2 Table 2-8 Figure 2-11	 1-2 1-6 2-2 2-9 2-12 2-23
	The "Design Environment" section was updated.	1-7
	The "Package Thermal Characteristics" was updated.	2-6